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With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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**Micro Commercial Components** 

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#### TSMBJ0505C-064

#### **Features**

- Oxide-Glass passivated Junction
- Bi-Directional protection in a single device
- Surge capabilities up to 80A@10/1000us or 250A@8/20us
- High Off-State impedance and Low On-State voltage
- Plastic material has UL flammability classification 94V-0

### Transient Voltage Protection Device 58 Volts

#### **Mechanical Data**

Case : Molded plastic

Polarity: None cathode band denotes

• Approx Weight: 0.093grams

#### **Maximum Ratings**

Characteristic	Symbol	Value	Unit
Non-repetitive peak impulse current	lpp	80A	10/1000us
Non-repetitive peak On-state current	I <sub>TSM</sub>	30A	8.3ms, one-half cycle
Operating temperature range	$T_{OP}$	-40~150°C	•
Junction and storage temperature range	$T_J$ , $T_{STG}$	-55~150°C	

## DO-214AA (SMB)

DIMENSIONS					
	INCHES		MM		
DIM	MIN	MAX	MIN	MAX	NOTE
Α	.078	.096	2.00	2.44	
В	.077	.083	1.96	2.10	
С	.002	.008	.05	.20	
D		.02		.51	
E	.030	.060	.76	1.52	
F	.065	.091	1.65	2.32	
G	.205	.220	5.21	5.59	
Η	.160	.180	4.06	4.57	
J	.130	.155	3.30	3.94	

# SUGGESTED SOLDER PAD LAYOUT 0.090" 0.070"

#### **Thermal Resistance**

Characteristic	Symbol	Value	Unit
Thermal Resistance junction to lead	$R_{ hetaJL}$	20°C/W	
Thermal Resistance junction to ambient	$R_{ heta JA}$	100°C/W	On recommended pad layout
Typical positive temperature coefficient for breakdown voltage	∆V <sub>BR</sub> /∆TJ	0.1%/℃	

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#### TSMBJ0505C-064



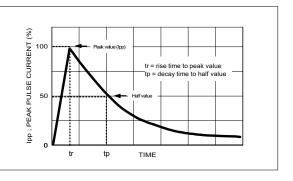
**Micro Commercial Components** 

#### ELECTRICAL CHARACTERISTIC @25°C Unless otherwise specified

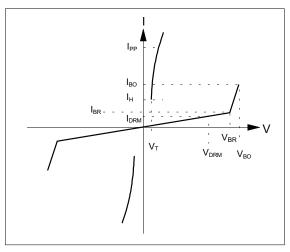
Parameter	Rated Repetitive Off -state Voltage	•	Breakover Voltage	On-State Voltage @I <sub>T</sub> =1.0A	Breakover Current	Holding Current	Off-State Capacitance
Symbol	$V_{DRM}$	I <sub>DRM</sub>	$V_{BO}$	$V_T$	I <sub>BO+</sub>	I <sub>H-</sub>	CJ
Units	Volts	uA	Volts	Volts	mA	mA	pF
Limit	Max	Max	Max	Max	Max	Min	Тур.
TSMBJ0505C-064	58	5	77	5	800	150	140

#### MAXIMUM RATED SURGE WAVEFORM

W DUNION TO THE DOUBLE TO THE OTHER				
Waveform	Standard	Ipp (A)		
2/10 us	GR-1089-CORE	250		
8/20 us	IEC 61000-4-5	250		
10/160 us	FCC Part 68	150		
10/700 us	ITU-T K20/21	100		
10/560 us	FCC Part 68	100		
10/1000 us	GR-1089-CORE	80		



Symbol	Parameter
$V_{DRM}$	Stand-off voltage
I <sub>DRM</sub>	Leakage current at stand-off voltage
$V_{BR}$	Breakdown voltage
I <sub>BR</sub>	Breakdown current
V <sub>BO</sub>	Breakover voltage
I <sub>BO</sub>	Breakover current
I <sub>H</sub>	Holding current NOTE: 1
V <sub>T</sub>	On state voltage
I <sub>PP</sub>	Peak pulse current
Co	Off-state capacitance NOTE: 2



#### NOTE

<sup>1.1</sup>  $_{\rm H}$  > ( V  $_{\rm L}$  / R  $_{\rm L}$ ) If this criterion is not obeyed, the TSPD triggers but does not return correctly to high-resistance state. The surge recovery time. It does not exceed 30ms.

<sup>2.</sup> Off-state capacitance measured at f=1.0MHz , 1.0Vrms signal , VR=2Vdc bias.

#### TSMBJ0505C-064



#### **Micro Commercial Components**

Fig.1 - Off-State Current v.s Junction Temperature

100

(V)

10

10

V)

VORM = 50V

0.001

0.001

-25

0 25 50 75 100 125 150

Tj., JUNCTION TEMPERATURE (°C)

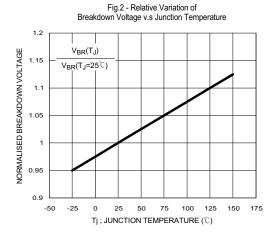


Fig. 3 - Relative Variation of Breakover Voltage v.s Junction Temperature

1.1

VBO(TJ)

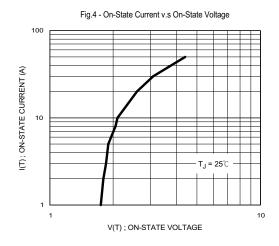
VBO(TJ=25°C)

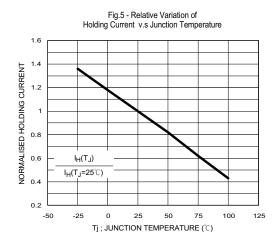
VBO(TJ=25°C)

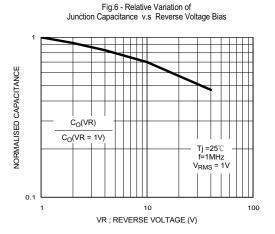
0.95

-50 -25 0 25 50 75 100 125 150 175

Tj; JUNCTION TEMPERATURE (°C)



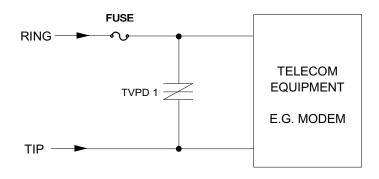


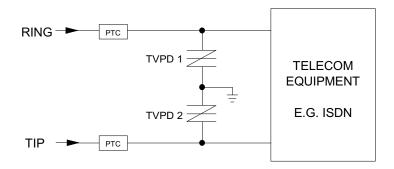


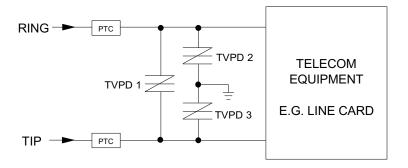
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#### TYPICAL APPLICATION CIRCUITS







The PTC (Positive Temperature Coefficient) is an overcurrent protection device.